

N- Channel Enhancement Mode MOSFET
◆ DESCRIPTION

The MT2502 is the N-Channel logic enhancement mode power field effect transistor are produced using high cell density, DMOS trench technology.

This high density process is especially tailored to minimize on-state resistance.

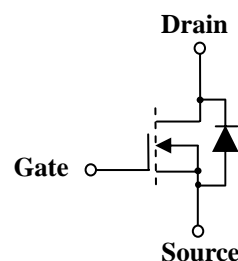
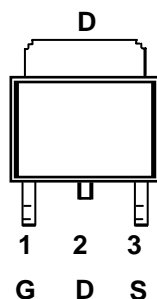
These devices are particularly suited for low voltage applications such as cellular phone and notebook computer power management and other Battery powered circuits, and low in-line power loss are needed in a very small outline surface mount package.

◆ FEATURES

- 100V/10A, $R_{DS(ON)} = 150m\Omega @ V_{GS} = 10V$
- 100V/10A, $R_{DS(ON)} = 175m\Omega @ V_{GS} = 5V$
- Super high density cell design for extremely ultra low $R_{DS(ON)}$
- Exceptional on-resistance and maximum DC current capability
- TO-252 package design

◆ APPLICATIONS

- POWER Management
- Portable Equipment
- DC/DC Converter
- Load Switch
- DSC

◆ PIN CONFIGURATION
TO-252(Top Site)


N- Channel Enhancement Mode MOSFET
◆ ABSOLUTE MAXIMUM RATINGS

 (T_A=25°C Unless Otherwise Noted)

Parameter S		ymbol	Maximum	Unit
Drain-Source Voltage		V _{DS} 100		V
Gate-Source Voltage		V _{GS} ±30		V
Continuous Drain Current	T _A = 25°C	I _D	10	A
	T _A = 100°C		7	
Pulsed Drain Current ^A		I _{DM}	40	A
Avalanche Current		I _{AS}	12	A
Avalanche Energy(L=0.1mH, I _D =12A,R _G =25Ω) E		A _S	7.2	mJ
Repetitive Avalanche Energy ^B (L=0.05mH) E		A _R	3.6	
Power Dissipation	T _A = 25°C	P _D	35	W
	T _A = 100°C		15	
Operating junction temperature range		T _J	- 55 to 175	°C
Storage temperature range		T _{STG}	- 55 to 175	°C

Note ^A: Pulse width limited by maximum junction temperature.
^B: Duty cycle ≤ 1%.

◆ THERMAL RESISTANCE RATINGS

Thermal Resistance	Symbol	Maximum	Unit
Junction-to-Case R	θ _{JC} 4.2		°C/W
Junction-to-Ambient R	θ _{JA} 62.5		°C/W

◆ ORDERING INFORMATION

Device Packag	e	Shipping
MT2501	TO-252	2,500 PCS / Tape & Reel

N- Channel Enhancement Mode MOSFET
◆ ELECTRICAL CHARACTERISTICS

 (T_A=25°C Unless Otherwise Noted)

Parameter Sy	mbol	Test Conditions	Min.	Typ.	Max.	Unit
Static Parameters						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = -250μA 100		-	-	V
Gate Threshold Voltage	V _{GS(th)}	V _{GS} = V _{DS} , I _D = -250μA 1		2	3	V
Gate Current	I _{GSS}	V _{DS} = 0V, V _{GS} = ± 30V	-	-	±100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 80V, V _{GS} = 0 V	-	-	1	μA
		V _{DS} = 70V, V _{GS} = 0V, T _J = 125°C	--		25	
On-State Drain Current ^A	I _{D(ON)}	V _{DS} = 10V, V _{GS} = 10V	10	-	-	A
Drain-Source On Resistance ^A	R _{DS(ON)}	V _{GS} = 10V, I _D = 10A	-	130	150	mΩ
		V _{GS} = 5V, I _D = 10A	-	150	175	
Forward Trans conductance ^A	g _{fs}	V _{DS} = 5V, I _D = 10A	-	8	-	S
Dynamic Parameters						
Input Cap.	C _{iss} -	V _{DS} = 25V, V _{GS} = 0V, f = 1MHz		1070	-	pF
Output Cap.	C _{oss} -		- 40	52	-	
Reverse Transfer Cap.	C _{rss}		-	-	-	
Gate Resistance R _g		V _{GS} = 15mV, V _{DS} = 0V, f = 1MHz	- 2.0		-	Ω
Total Gate Charge ^{A,B}	Q _g -	V _{DS} = 80V, V _{GS} = 10V, I _D = 10A		18.8	-	nC
Gate-Source Charge ^{A,B}	Q _{gs} -		- 4.5	3.8	-	
Gate-Drain Charge ^{A,B}	Q _{gd}			-	-	
Turn-On Time ^{A,B}	T _{D(ON)} -	V _{DS} = 50V, I _D = 1A, V _{GS} = 10V, R _{GS} = 6Ω		15	-	nS
Rise Time ^{A,B}	t _r -			35	-	
Turn-Off Time ^{A,B}	T _{D(OFF)} -			25	-	
Fail Time ^{A,B}	t _f		- 25		-	
Source-Drain Diode Ratings And Characteristics						
Continuous Current	I _S		-	-	10	A
Pulsed Current ^C	I _{SM}		-	-	40	
Forward Voltage ^A	V _{SD}	I _F = I _S , V _{GS} = 0V	-	-	1.3	V
Reverse Recovery Time	t _{rr}	I _F = 10A, dI _F /dt=100A/μS	-	120	-	nS
Reverse Recovery Charge	Q _{rr}		- 520		-	nC

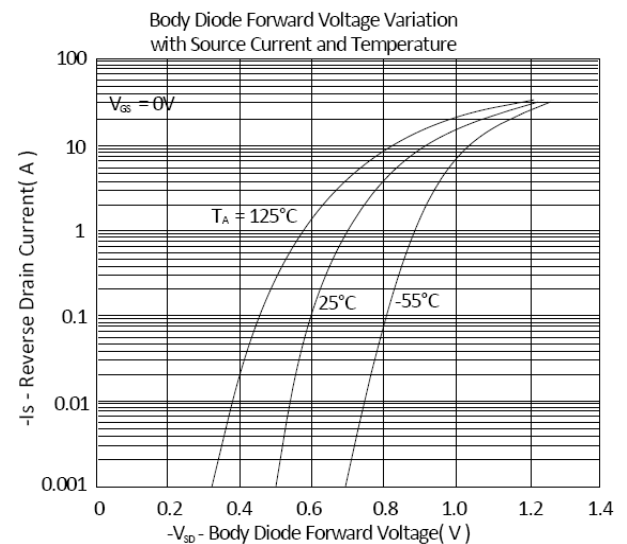
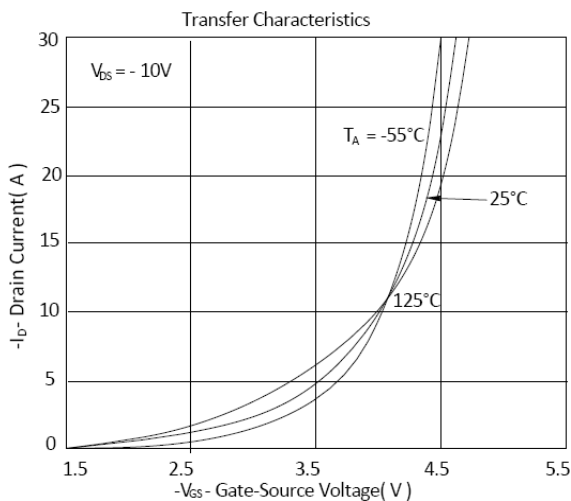
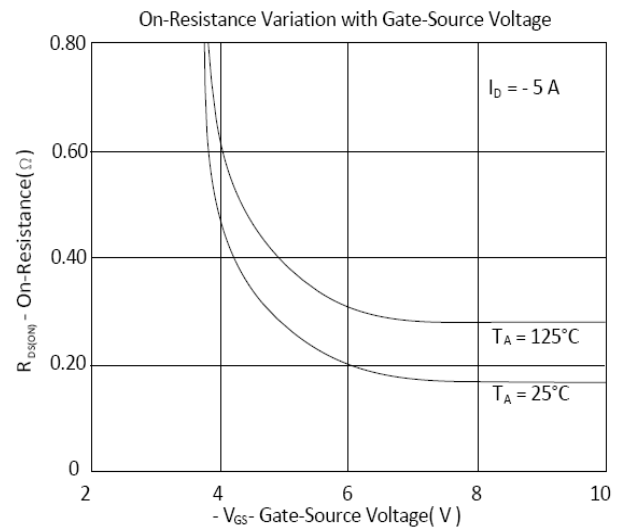
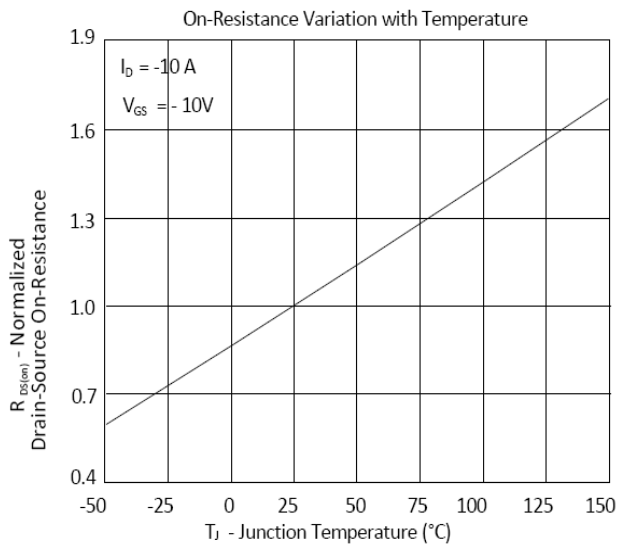
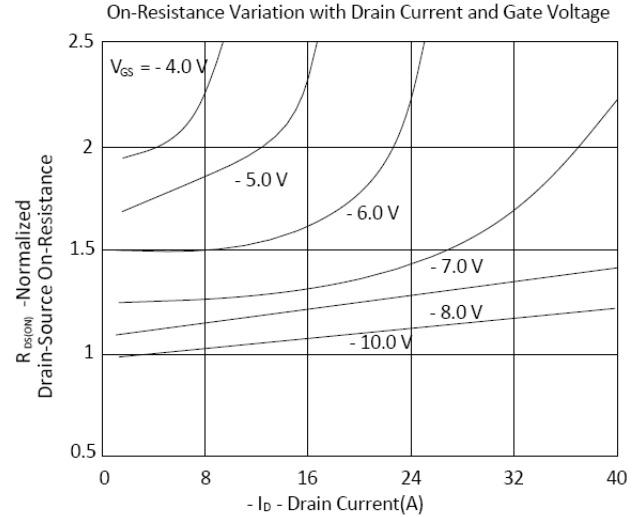
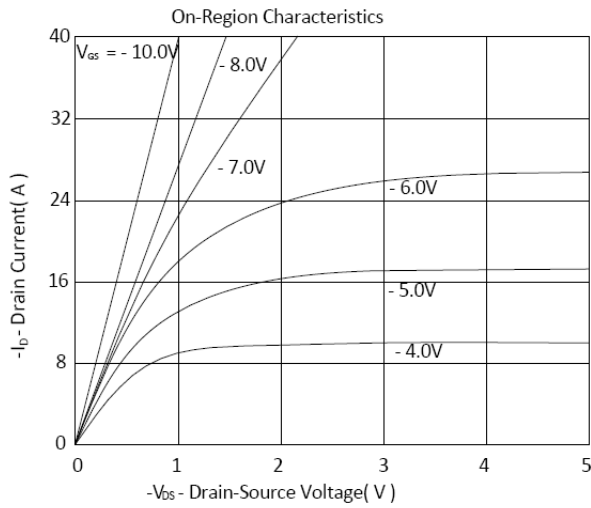
 Note ^A: Pulse test: Pulse width ≤ 300μsec, Duty Cycle ≤ 2%

^B: Independent of operating temperature

^C: Pulse width limited by maximum junction temperature.

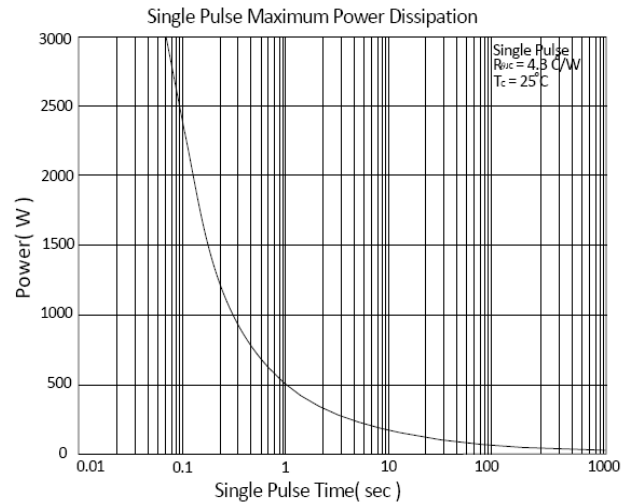
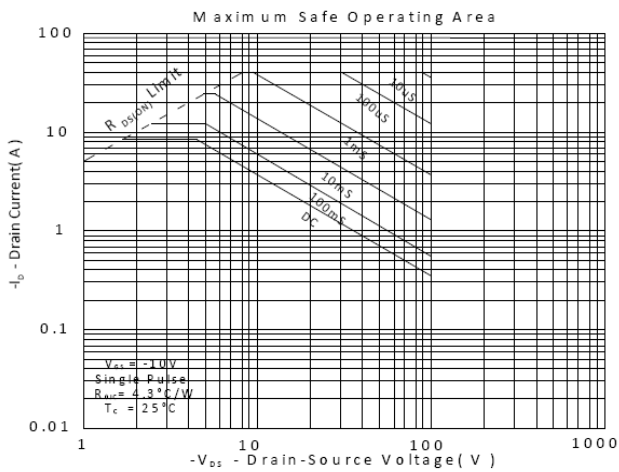
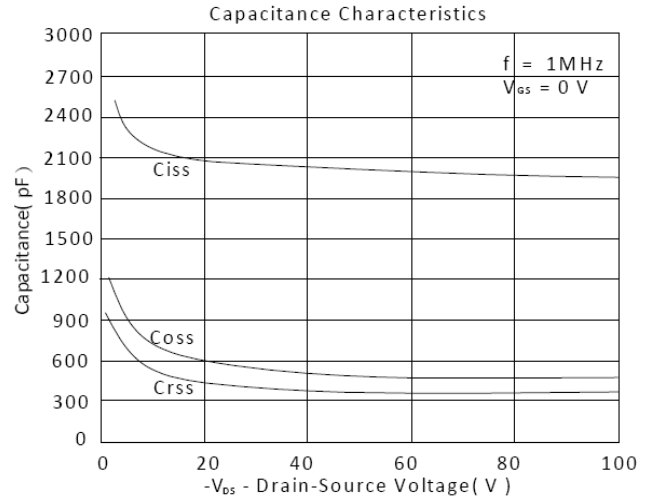
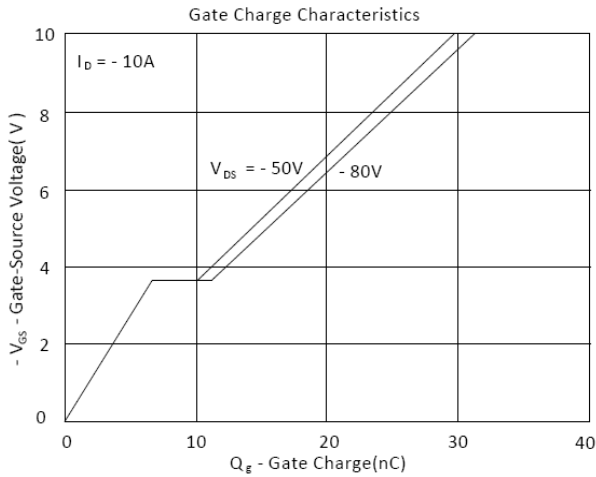
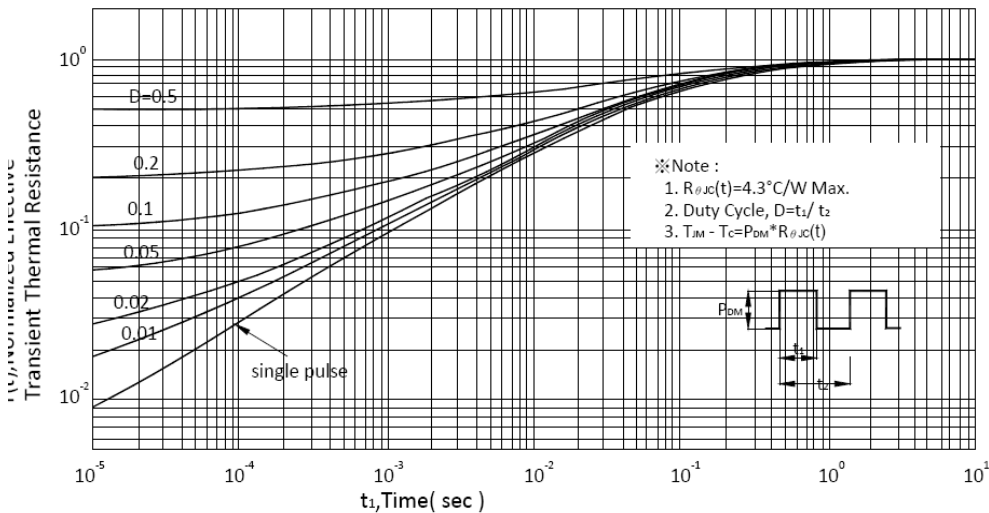
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◆ TYPICAL CHARACTERISTICS

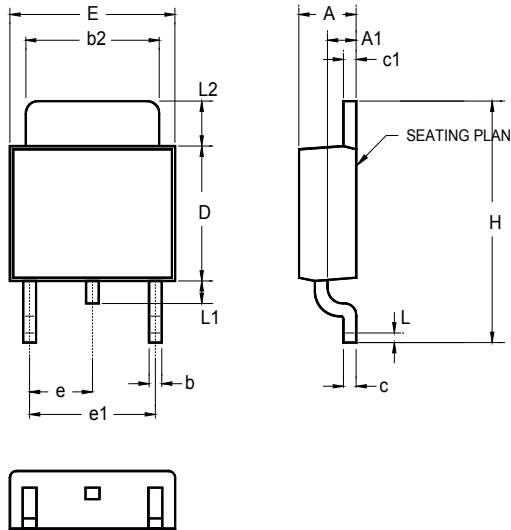
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◆ TYPICAL CHARACTERISTICS

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Transient Thermal Response Curve


N- Channel Enhancement Mode MOSFET
◆ PHYSICAL DIMENSIONS
3-Pin Surface Mount TO-252 (B)


	INCHES MILLIMETERS					
	MIN	TYP	MAX	MIN	TYP	MAX
A	0.086	-	0.094	2.18	-	2.39
A1	0.040	-	0.050	1.02	-	1.27
b	-	0.024	-	-	0.61	-
b2	0.205	-	0.215	5.21	-	5.46
c	0.018	-	0.023	0.46	-	0.58
c1	0.018	-	0.023	0.46	-	0.58
D	0.210	-	0.220	5.33	-	5.59
E	0.250	-	0.265	6.35	-	6.73
e	0.090 BSC		2.29 BSC			
e1	0.180 BSC		4.58 BSC			
H	0.370	-	0.410	9.40	-	10.41
L	0.020	-	-	0.51	-	-
L1	0.025	-	0.040	0.64	-	1.02
L2	0.060	-	0.080	1.52	-	2.03